

IN THE CLAIMS

Please amend the claims to read as follows:

1 1. (Twice Amended) A method of marking a chip having surfaces comprising the following  
2 steps:  
3 forming internal marking indicia on a marking location upon an exterior surface of the  
4 chip for identification of the chip, and  
5 forming a non-black, optically transmissive encapsulating material over at least the  
6 marking location on the one exterior surface of the chip which non-black, optically  
7 transmissive material cannot be easily scraped off of the chip for prevention of replacement of  
8 the internal marking indicia by different markings.

Bx / SUB C2  
1 3. (Twice Amended) The method of claim 1 wherein the non-black, optically transmissive  
2 encapsulating material is a protective encapsulating material adapted to provide protection  
3 from damage as the result of environmental and handling factors.

B5 / SUB C3  
1 6. (Twice Amended) The method of claim 1 wherein the non-black, optically transmissive  
2 material comprises a material such as epoxy which prevents remarking indicia or  
3 identification marks on the chip.

B6 / SUB C4  
1 12. (Twice Amended) A method of marking a chip having surfaces comprising:  
2 forming internal marking indicia on a marking location upon an exterior surface of the  
3 chip, and  
4 forming a non-black, optically transparent material colored with a particular color over  
5 at least the marking location on that exterior surface of the chip wherein the material colored  
6 with the particular color together with the marking indicia represents identification of the chip  
7 which non-black, optically transparent, colored material cannot be easily scraped off of the  
8 chip for prevention of replacement of the internal marking indicia by different markings.

1 13. (Twice Amended) A chip comprising:

2 the chip having exterior surfaces,

3 internal marking indicia formed on a marking location upon an exterior surface  
4 of the chip for identification of the chip, and

5 a non-black, optically transmissive material formed over at least the marking location  
6 on the one exterior surface of the chip which non-black, optically transmissive material cannot  
7 be easily scraped off for prevention of replacement of the internal marking indicia by different  
8 markings.

1 22. (Twice Amended) An electronic integrated circuit chip comprising:

2 a semiconductor, integrated circuit chip having surfaces including a planar front  
3 surface, a planar back surface and edges of the chip between the planar surfaces with at least  
4 one electrical contact site on a surface,

5 indicia marked upon an exterior marking portion of a surface of the chip for  
6 identification of the chip,

7 a non-black layer covering the exterior surface of the chip at least at the exterior  
8 marking portion thereof, the non-black layer being composed of a colored, optically  
9 transmissive material which non-black, optically transmissive material cannot be easily  
10 scraped off of the chip for prevention of replacement of the indicia by different markings and  
11 for preventing remarking the indicia on the exterior marking surface of the chip, and  
12 the indicia being visible through the non-black layer.

1 25. (Twice Amended) A chip comprising:

2 internal marking indicia formed on a marking location upon an exterior surface of the  
3 chip, and

4 a non-black, optically transparent material colored with a particular color formed over  
5 at least the marking location on that exterior surface of the chip wherein the material colored  
6 with the particular color together with the marking indicia represents identification of the chip  
7 which non-black, optically transmissive material cannot be easily scraped off of the chip for